



520 Park East Blvd. • P.O. Box 1147  
New Albany, IN 47150 USA  
812-944-6733 • 800-SAMTEC-9 • 812-948-5047  
[www.samtec.com](http://www.samtec.com) • email: [info@samtec.com](mailto:info@samtec.com)

For product or editorial information,  
please contact: Ty Atkins at  
[ty.atkins@samtec.com](mailto:ty.atkins@samtec.com)

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## **Samtec to Present New Products and Paper at DesignCon 2011**

Samtec, Inc. will participate in the DesignCon 2011 conference and exhibition featuring three new products and a 40-minute paper session on advanced transmission lines for improved signal integrity.

Eye Speed® HD (HDLSP, HDC Series) is the industry's densest I/O cable system offering superior signal integrity with HyperTransport™ HT 3.1 performance and 32 AWG low skew pair cable. Designed for heavy-duty handling, Eye Speed® HD is equipped with a rugged latching system and shielded for EMI protection.

Samtec's line of high speed, high density SEARAY™ open pin field arrays is now available in a right angle design that is ideal for micro backplane applications and press fit tail options with up to 500 I/Os and optional rugged features. Also in development is a 0,8mm (.0315") micro pitch SEARAY™ interconnect (SEAM8/SEAF8 Series) that uses 50 percent less board space while providing the same grounding and routing flexibility as the 1,27mm (.050")pitch arrays.

Available in Board-to-Board and Cable-to-Board interconnect solutions, the Edge Rate™ contact system is designed to optimize signal integrity in rugged applications, offers superior impedance, and reduces broadside coupling.

Samtec received a 2010 DesignVision Award in the Interconnect Technologies and Components category for its Bull's Eye™ high performance, low cost test system.

Visit Samtec at Booth 215 during the DesignCon 2011 show or [www.samtec.com/designcon](http://www.samtec.com/designcon) for more information on Samtec's signal integrity capabilities.